

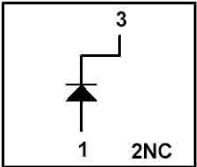


描述 / Descriptions

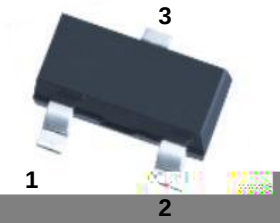
特征 / Features

用途 / Applications

内部等效电路 / Equivalent Circuit

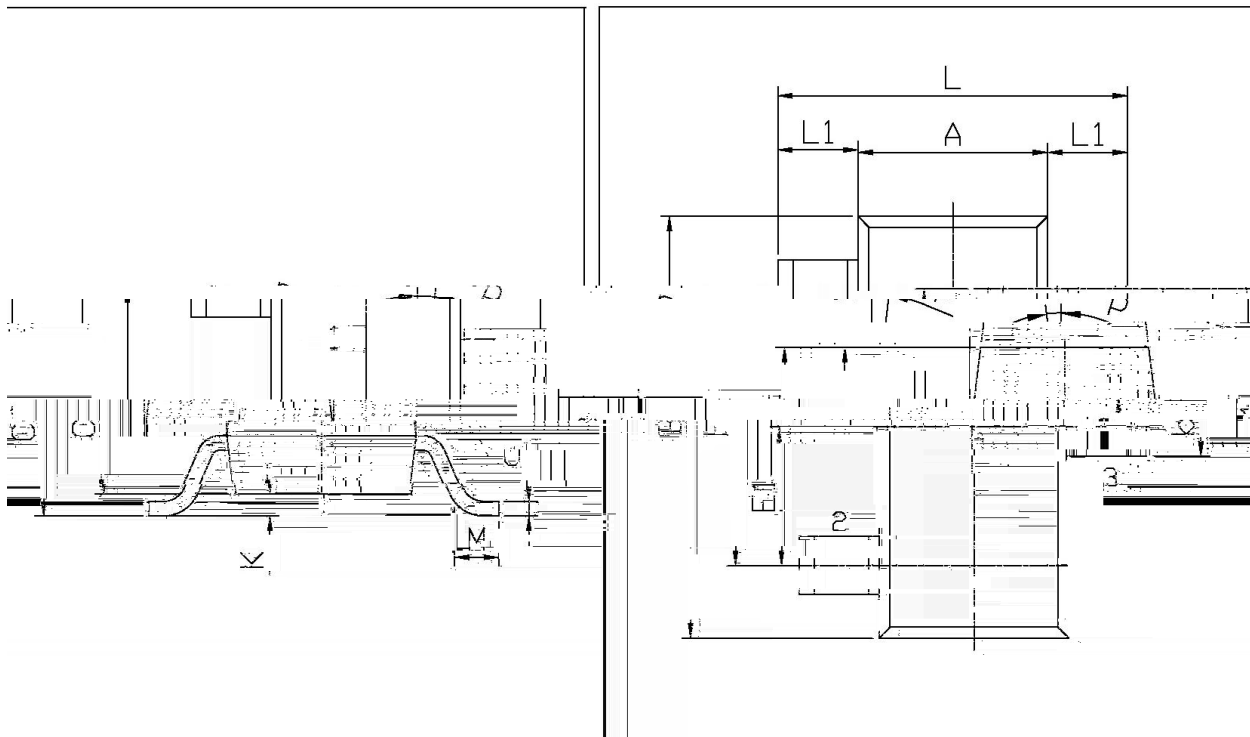
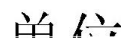


引脚排列 / Pinning



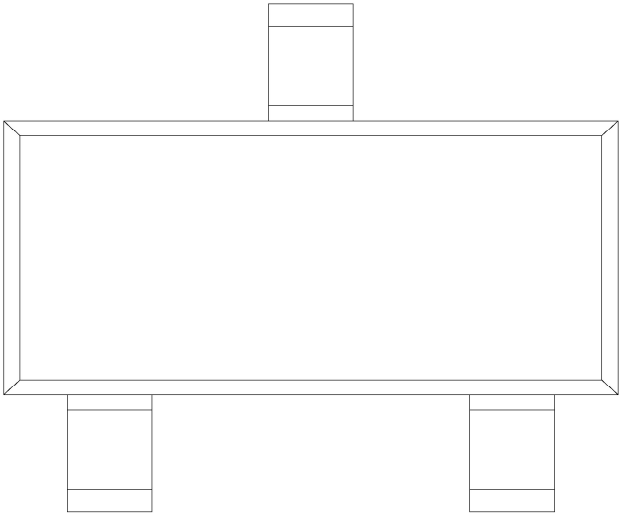
放大及印章代码 / h_{FE} Classifications & Marking

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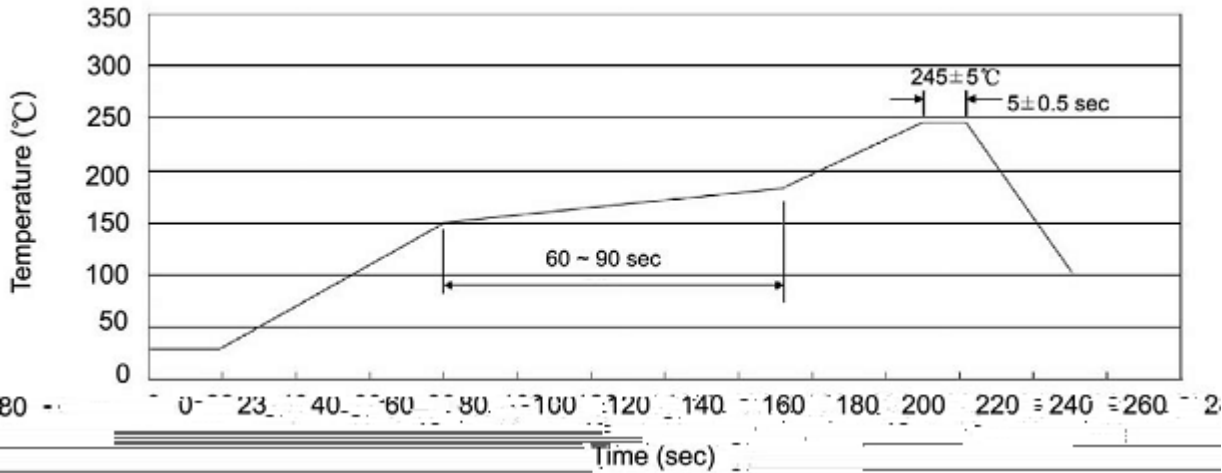


Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
L	2.2	2.7	C	1.30Max	
E1	0.45	0.65	G1	0.90	1.20
A	1.15	1.50	c	0.05	0.20
B	2.70	3.10	K	0	0.10
E	1.70	2.10	W	0.20MIN	
E1	0.85	1.05	P	7	
b	0.35	0.55			

印章说明 / Marking Instructions



回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

将元件安装在符合 JEDEC J-STD-020 的载板上，在 245±5℃ 下焊接 5±0.5 秒。

包装规格 / Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只卷盘	卷盘盒	只盒	盒箱	只箱		盒	箱
						"		

使用说明 / Notices